



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			


Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-06-09
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	IPD MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
USBUF01W6	HCWO*USBUF1C	A	ZS1A	2016-06-09
	Amount	UoM	Unit type	ST ECOPACK Grade
	6.00	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	1.8 - 1.15 - 0.8	3	gull wing	
Comment	Package: SOT 323 6LDS			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-17th December 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	HCWO*USBUFIC					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	0.180	mg	supplier	die	Silicon (Si)	7440-21-3		0.156	mg	866667	26000
				supplier	metallization	Aluminium (Al)	7429-90-5		0.021	mg	116667	3500
				supplier	Passivation	Silicon Oxide	7631-86-9		0.002	mg	11111	333
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.001	mg	5555	167
Lead-frame	Other inorganic materials	2.736	mg	supplier	alloy	Copper (Cu)	7440-50-8		2.642	mg	965643	440333
				supplier	alloy	Iron (Fe)	7439-89-6		0.062	mg	22661	10333
				supplier	alloy	Phosphorus (P)	12185-10-3		0.001	mg	366	167
				supplier	alloy	Zinc (Zn)	7440-66-6		0.003	mg	1096	500
				supplier	metallization	Silver (Ag)	7440-02-0		0.028	mg	10234	4667
Die Attach	Other inorganic materials	0.037	mg	supplier	glue	Silver (Ag)	7440-22-4		0.026	mg	702703	4333
				supplier	glue	methylene diacrylate	42594-17-2		0.009	mg	243243	1500
				supplier	glue	Dicyclopentenyl ethyl methacrylate	68586-19-6		0.001	mg	27027	167
				supplier	glue	Polymer of Polybutadiene + Anhydride	Proprietary		0.001	mg	27027	167
Bonding wire	Other inorganic materials	0.160	mg	supplier	wire	Copper (Cu)	7440-50-8		0.157	mg	981250	26167
				supplier	wire	Palladium (Pd)	7440-05-3		0.003	mg	18750	500
encapsulation	Other inorganic materials	2.701	mg	supplier	mold compound	Silica, vitreous	60676-86-0		2.304	mg	853017	384000
				supplier	mold compound	phenolic resin	29690-82-2		0.095	mg	35172	15833
				supplier	mold compound	epoxy resin	25068-38-6		0.108	mg	39985	18000
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		0.054	mg	19993	9000
				supplier	mold compound	carbon black	1333-86-4		0.005	mg	1852	833
				supplier	mold compound	Zinc hydroxide	20427-58-1		0.027	mg	9996	4500
Connections coating	Solder	0.186	mg	supplier	mold compound	Magnesium hydroxide	1309-42-8		0.108	mg	39985	18000
				supplier	solder alloy	Tin (Sn)	7440-31-5		0.186	mg	1000000	31000